Vishay Semiconductors

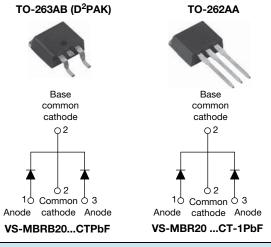
RoHS

COMPLIANT

HALOGEN

FREE

High Performance Schottky Rectifier, 2 x 10 A



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SHA

PRODUCT SUMMARY				
Package	TO-263AB (D ² PAK), TO-262AA			
I _{F(AV)}	2 x 10 A			
V _R	80 V, 90 V, 100 V			
V _F at I _F	0.70 V			
I _{RM} max.	15 mA at 125 °C			
T _J max.	150 °C			
Diode variation	Common cathode			
E _{AS}	8.0 mJ			

FEATURES

- 150 °C T_J operation
- Low forward voltage drop
- High frequency operation
- Center tap D²PAK and TO-262 packages
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION

This center tap Schottky rectifier has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 150 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS						
SYMBOL	CHARACTERISTICS	VALUES	UNITS			
I _{F(AV)}	Rectangular waveform (per device)	20	Δ			
I _{FRM}	T _C = 133 °C (per leg)	20	A			
V _{RRM}		80 to 100	V			
I _{FSM}	t _p = 5 μs sine	850	А			
V _F	10 A _{pk} , T _J = 125 °C	0.70	V			
TJ	Range	-65 to +150	°C			

VOLTAGE RATINGS						
PARAMETER	SYMBOL	VS-MBRB2080CTPbF VS-MBR2080CT-1PbF	VS-MBRB2090CTPbF VS-MBR2090CT-1PbF	VS-MBRB20100CTPbF VS-MBR20100CT-1PbF	UNITS	
Maximum DC reverse voltage	V _R	80	90	100	V	
Maximum working peak reverse voltage	V _{RWM}	00	90	100	v	

ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL TEST CONDITIONS		VALUES	UNITS		
Maximum average per leg		$T_{\rm C} = 133 ^{\circ}\text{C}$, rated $V_{\rm B}$	10			
forward current per device	I _{F(AV)}	$\Gamma_{\rm C} = 105$ °C, falled $V_{\rm R}$	20	1		
Peak repetitive forward current per leg	I _{FRM}	Rated V _R , square wave, 20 kHz, T _C = 133 °C	20			
Non-repetitive peak surge current		5 μs sine or 3 μs rect. pulse Following any rated load cond and with rated V _{RRM} applied	dition 850	А		
Non-repetitive peak surge current	IFSM	Surge applied at rated load conditions half wave, single phase, 60 Hz	150			
Peak repetitive reverse surge current	I _{RRM}	2.0 μs, 1.0 kHz	0.5			
Non-repetitive avalanche energy per leg	E _{AS}	T _J = 25 °C, I _{AS} = 2 A, L = 12 mH	24	mJ		

Revision: 18-Oct-16

Document Number: 94306

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ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST C	VALUES	UNITS		
		10 A	T ₁ = 25 °C	0.80	V	
Maximum forward voltage drop	V _{FM} ⁽¹⁾	20 A	1j=25 0	0.95		
Maximum forward voltage drop	V FM (")	10 A	T _{.1} = 125 °C	0.70		
		20 A	1j = 125 C	0.85		
Maximum instantaneous	I _{RM} ⁽¹⁾	T _J = 25 °C	Rated DC voltage	0.10	mA	
reverse current	IRM (")	T _J = 125 °C	haled DC vollage	6		
Threshold voltage	V _{F(TO)}			0.433	V	
Forward slope resistance	r _t	$T_J = T_J maximum$		15.8	mΩ	
Maximum junction capacitance	CT	V_R = 5 V_{DC} (test signal range 100 kHz to 1 MHz), 25 °C		400	pF	
Typical series inductance	L _S	Measured from top of te	8.0	nH		
Maximum voltage rate of change	dV/dt	Rated V _R		10 000	V/µs	

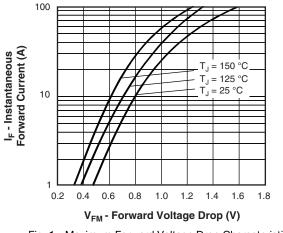
Note

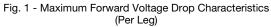
 $^{(1)}\,$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

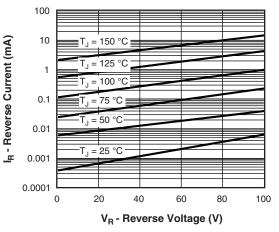
THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum junction temperature r	range T _J		-65 to +150	*		
Maximum storage temperature ra	ange T _{Stg}		-65 to +175	°C		
Maximum thermal resistance, junction to case per leg	R _{thJC}	DC operation	2.0			
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, smooth and greased	0.50	°C/W		
Maximum thermal resistance, junction to ambient	R _{thJA}	DC operation	50			
Approvimeto weight			2	g		
Approximate weight			0.07	oz.		
	imum	Non-lubricated threads	6 (5)	kgf · cm (lbf · in)		
Mounting torque max	kimum	Non-Iubricated threads	12 (10)			
Marking davias		Case style D ² PAK	MBRB2	0100CT		
Marking device		Case style TO-262	MBR201	00CT-1		

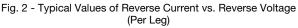


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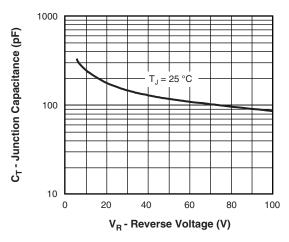
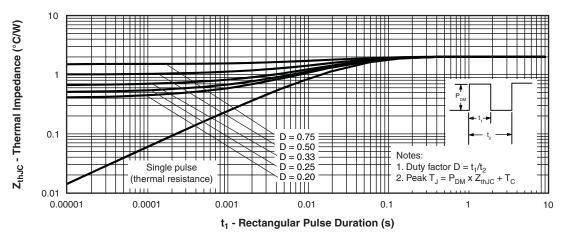
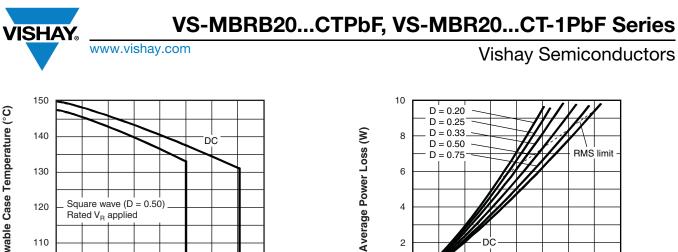


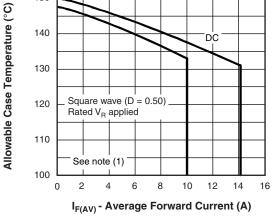
Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

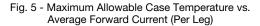




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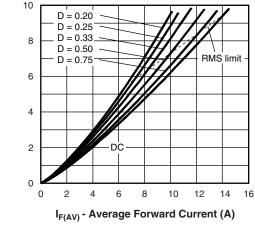


Fig. 6 - Forward Power Loss Characteristics (Per Leg)

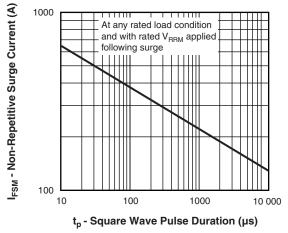


Fig. 7 - Maximum Non-Repetitive Surge Current (Per Leg)

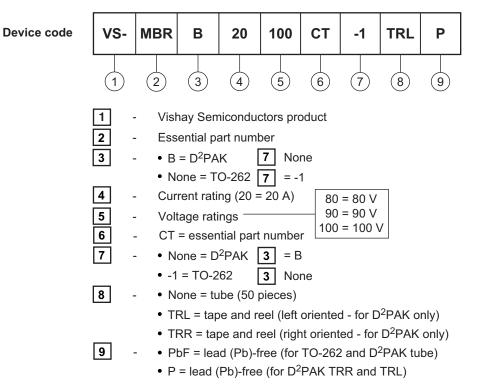
Note

⁽¹⁾ Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$; Pd = forward power loss = $I_{F(AV)} \times V_{FM}$ at $(I_{F(AV)}/D)$ (see fig. 6); Pd_{BEV} = inverse power loss = $V_{B1} \times I_{B} (1 - D)$; I_{B} at V_{B1} = rated V_{B1}



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ORDERING INFORMATION TABLE

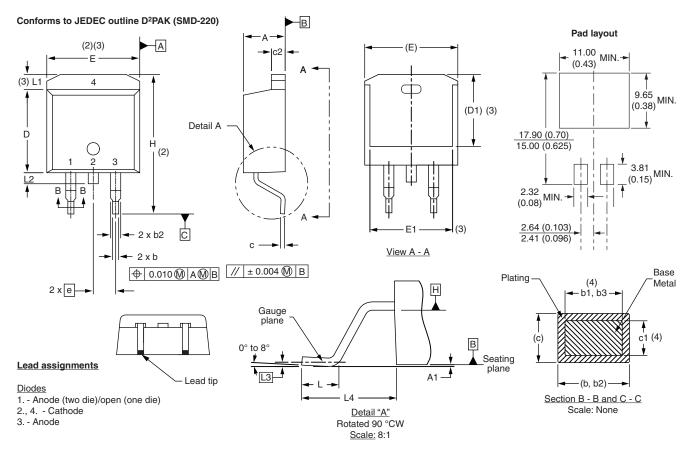


LINKS TO RELATED DOCUMENTS				
Dimensions www.vishay.com/doc?95014				
Part marking information	www.vishay.com/doc?95008			
Packaging information	www.vishay.com/doc?95032			

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D²PAK, TO-262



DIMENSIONS - D²PAK in millimeters and inches

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SYMBOL	MILLIMETERS INCHES		NOTES		
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
с	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

Notes

- $^{(1)}\,$ Dimensioning and tolerancing per ASME Y14.5 M-1994 $\,$
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}\,$ Thermal pad contour optional within dimension E, L1, D1 and E1
- ⁽⁴⁾ Dimension b1 and c1 apply to base metal only
- ⁽⁵⁾ Datum A and B to be determined at datum plane H
- ⁽⁶⁾ Controlling dimension: inch

SYMBOL	MILLIMETERS		RS INCHES		NOTES
STIVIDUL	MIN.	MAX.	MIN.	MAX.	NULES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

(7) Outline conforms to JEDEC outline TO-263AB

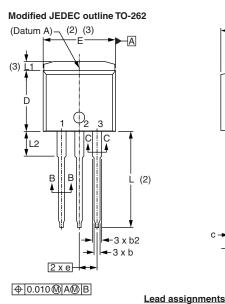
Outline Dimensions

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D²PAK, TO-262



DIMENSIONS - TO-262 in millimeters and inches

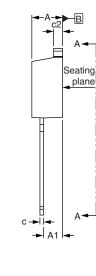


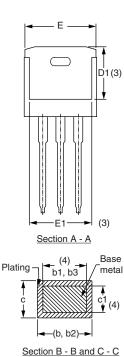
Lead tip

Diodes

3. - Anode

2., 4. - Cathode





Scale: None MILLIMETERS INCHES SYMBOL NOTES MIN. MAX. MIN. MAX. 4.06 4.83 0.160 0.190 А A1 2.03 3.02 0.080 0.119 b 0.51 0.99 0.020 0.039 0.51 0.89 0.020 0.035 4 b1 h2 1.14 1.78 0.045 0.070 b3 1.14 1.73 0.045 0.068 4 0.38 0.74 0.015 0.029 С 0.38 0.58 0.015 0.023 4 c1 1.14 0.045 0.065 c2 1.65 D 8.51 9.65 0.335 0.380 2 0.270 D1 6.86 8.00 0.315 3 Е 9.65 10.67 0.380 0.420 2, 3 E1 7.90 8.80 0.311 0.346 3 е 2.54 BSC 0.100 BSC L 13.46 14.10 0.530 0.555 L1 1.65 0.065 -3 L2 3.56 3.71 0.140 0.146 Notes

1. - Anode (two die)/open (one die)

⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽²⁾ Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

⁽³⁾ Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

⁽⁵⁾ Controlling dimension: inches

(6) Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline

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